

HVC383B

Variable Capacitance Diode for VCO

REJ03G0092-0100Z

(Previous: ADE-208-823)

Rev.1.00

Sep.17.2003

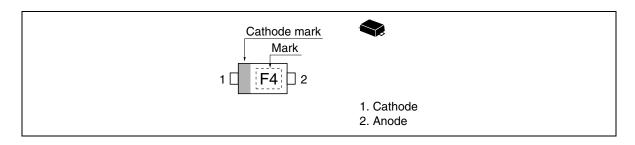
Features

- High capacitance ratio. (n = 2.0 min)
- Low series resistance. (rs = $0.5 \Omega \text{ max}$)
- Good C-V linearity.
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC383B	F4	UFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

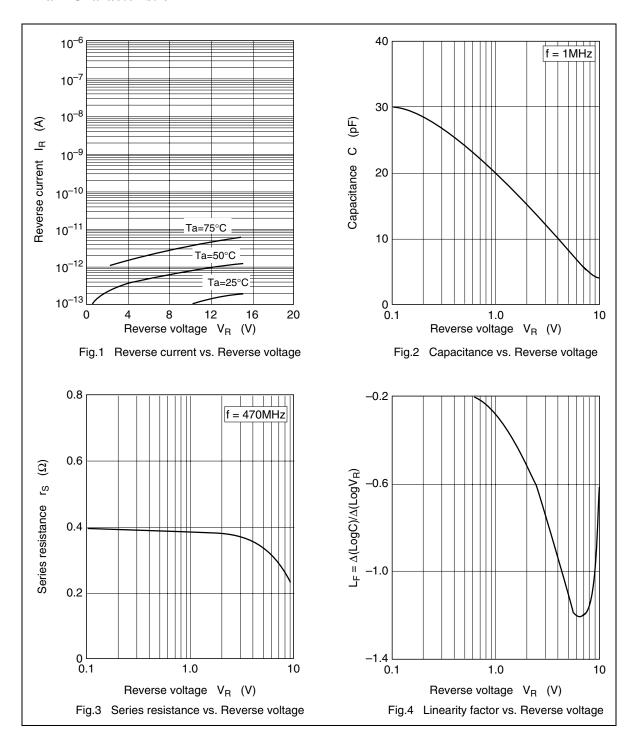
Item	Symbol	Value	Unit
Reverse voltage	V_R	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

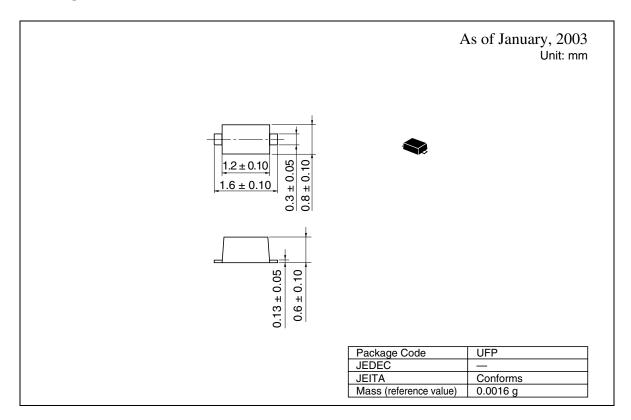
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 15 V
	I _{R2}		_	100		V _R = 15 V, Ta = 60°C
Capacitance	C ₁	19.0	_	21.0	рF	V _R = 1 V, f = 1 MHz
	C ₄	8.50	_	10.0		V _R = 4 V, f = 1 MHz
	C ₇	4.50	_	5.5		V _R = 7 V, f = 1 MHz
Capacitance ratio	n ₁	2.00	_	_	_	C ₁ /C ₄
	n ₂	3.50	_	_	_	C ₁ /C ₇
Series resistance	r _s	_	_	0.5	Ω	V _R = 1 V, f = 470 MHz

Main Characteristic



Package Dimensions



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Renesas Technology America, Inc. 450 Holger Way, San Jose, CA 95134-1368, U.S.A Tel: <1> (408) 382-7500 Fax: <1> (408) 382-7501

Renesas Technology Europe Limited.

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, United Kingdom Tel: <44> (1628) 585 100, Fax: <44> (1628) 585 900

Renesas Technology Europe GmbH Dornacher Str. 3, D-85622 Feldkirchen, Germany Tel: <49> (89) 380 70 0, Fax: <49> (89) 929 30 11

Renesas Technology Hong Kong Ltd. 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Hong Kong Tel: <852> 2265-6688, Fax: <852> 2375-6836

Renesas Technology Taiwan Co., Ltd. FL 10, #99, Fu-Hsing N. Rd., Taipei, Taiwan Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd. 26/F., Ruijin Building, No.205 Maoming Road (S), Shanghai 200020, China Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.
1, Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001